1.6X0.8mm SMD CHIP LED LAMP



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- •1.6mmX0.8mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS / REEL .
- •LEAD AND CADMIUM FREE.

Description

KP-1608PBC

The Blue source color devices are made with InGaN on SiC Light Emitting Diode.

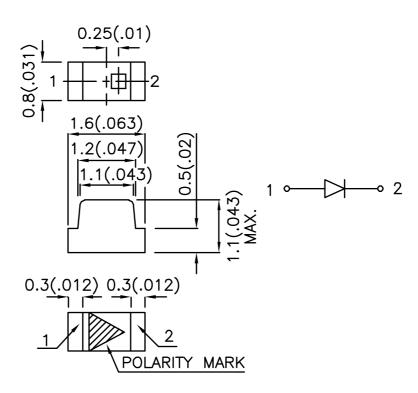
BLUE

- Static electricity and surge damage the LEDS.
- It is recommended to use a wrist band or

anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).

2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.

3. Specifications are subject to change without notice.

SPEC NO: DSAB1013 APPROVED: J. Lu REV NO: V.5 CHECKED: Allen Liu DATE: MAY/06/2004 DRAWN: L.L.NIE

Selection Gui	de				
Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	201/2
KP-1608PBC	BLUE (InGaN)	WATER CLEAR	18	45	120°

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at TA=25°C

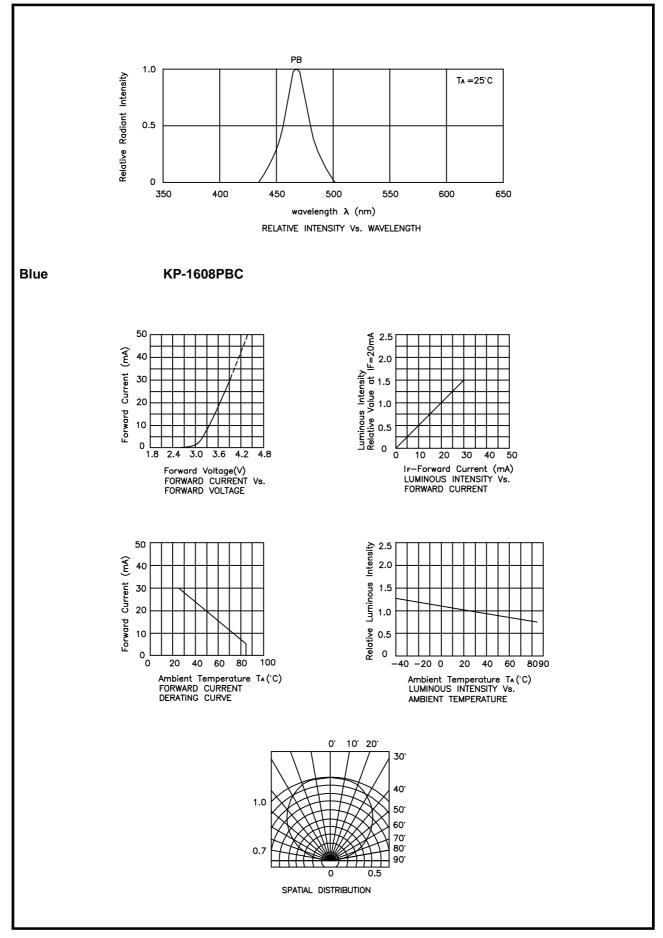
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	468		nm	IF=20mA
λD	Dominate Wavelength	Blue	470		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue	25		nm	IF=20mA
С	Capacitance	Blue	65		pF	VF=0V;f=1MHz
Vf	Forward Voltage	Blue	3.65	4.2	V	IF=20mA
lr	Reverse Current	Blue		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Units
Power dissipation	102	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
perating / Storage Temperature -40°C To +85°C		

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



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KP-1608PBC SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and

second soldering process.

